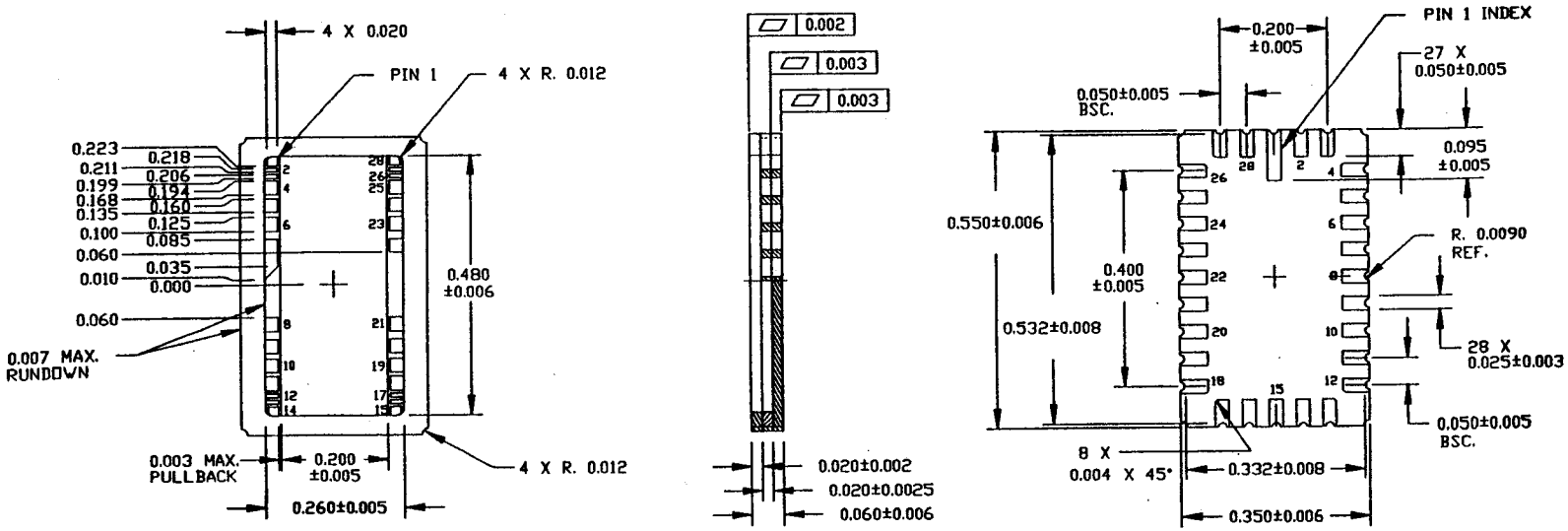
SSM P/N LCC02852

NOTES:
1. INTERPRET DRAWING PER DOD-STD-100.
2. DIMENSIONS ARE TYPICAL FOR ALL QUADRANTS UNLESS OTHERWISE SPECIFIED.
3. BOND FINGERS AND SEAL RING WILL BE PLATED WITH GOLD (80 μ IN. MIN.) OVER NICKEL (80 μ IN. MIN.). DIE ATTACH CAVITY WILL HAVE NO METALIZATION.
4. DIE ATTACH CAVITY AND SEAL RING WILL BE ELECTRICALLY ISOLATED.



UNLESS OTHERWISE SPECIFIED	DESIGNED BY	DATE	
ALL DIMENSIONS ARE IN INCHES STANDARD TOLERANCES ON DECIMALS XX ± / XXX ± 0.003 XXXX ± 0.0010 ANGLES ± /	DRAWN HTN	DATE 07/10/98	
	CHK BY	DATE	TITLE 28 LD RECT. LCC, 200 X 480
	APPROVED BY	DATE 7/21/98	
MATERIAL SEE NOTES	APPROVED BY	DATE	SIZE B / PART NO. / DWG NO 51-20064 / REV *B
FINISH SEE NOTES			SCALE 5: 1 / SHEET 1 OF 1

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